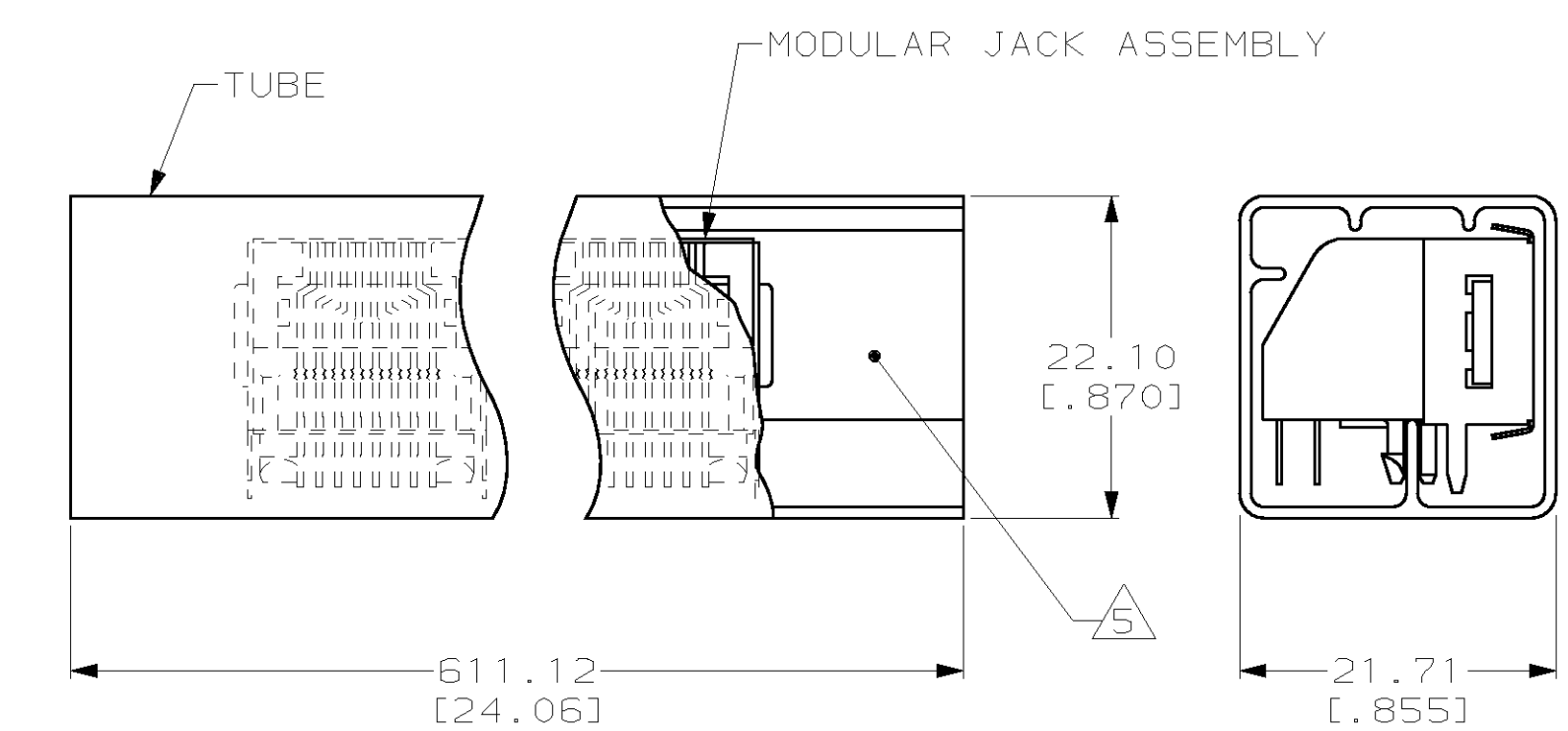
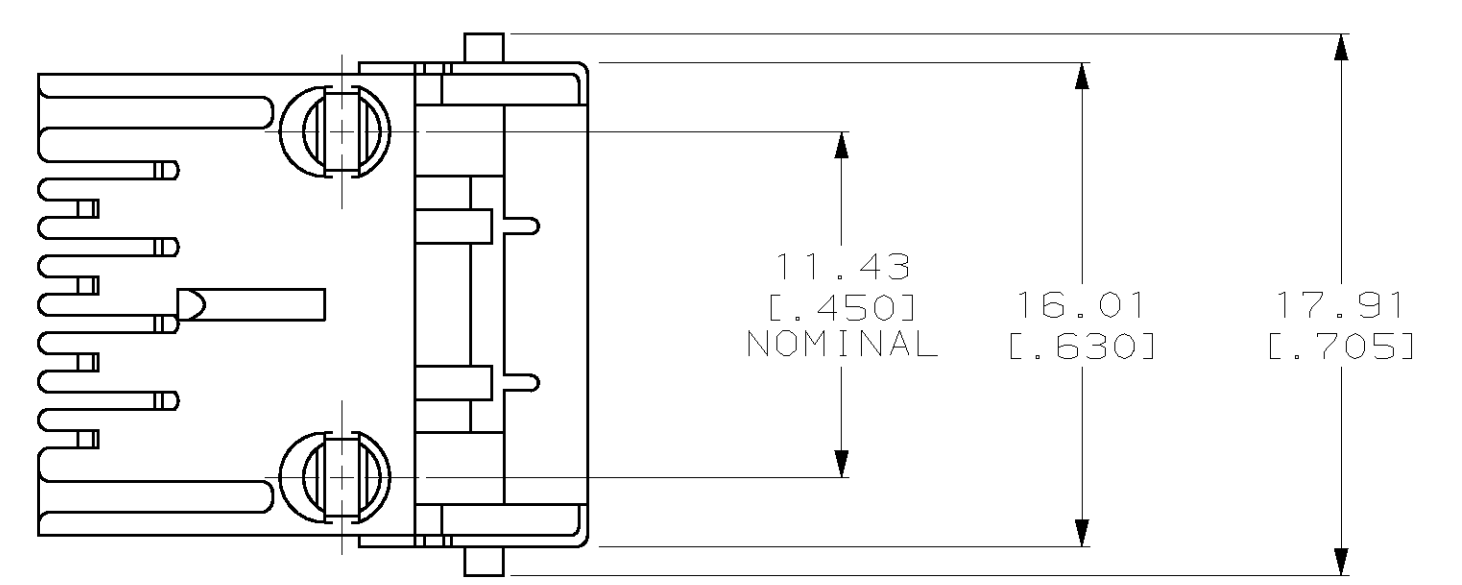
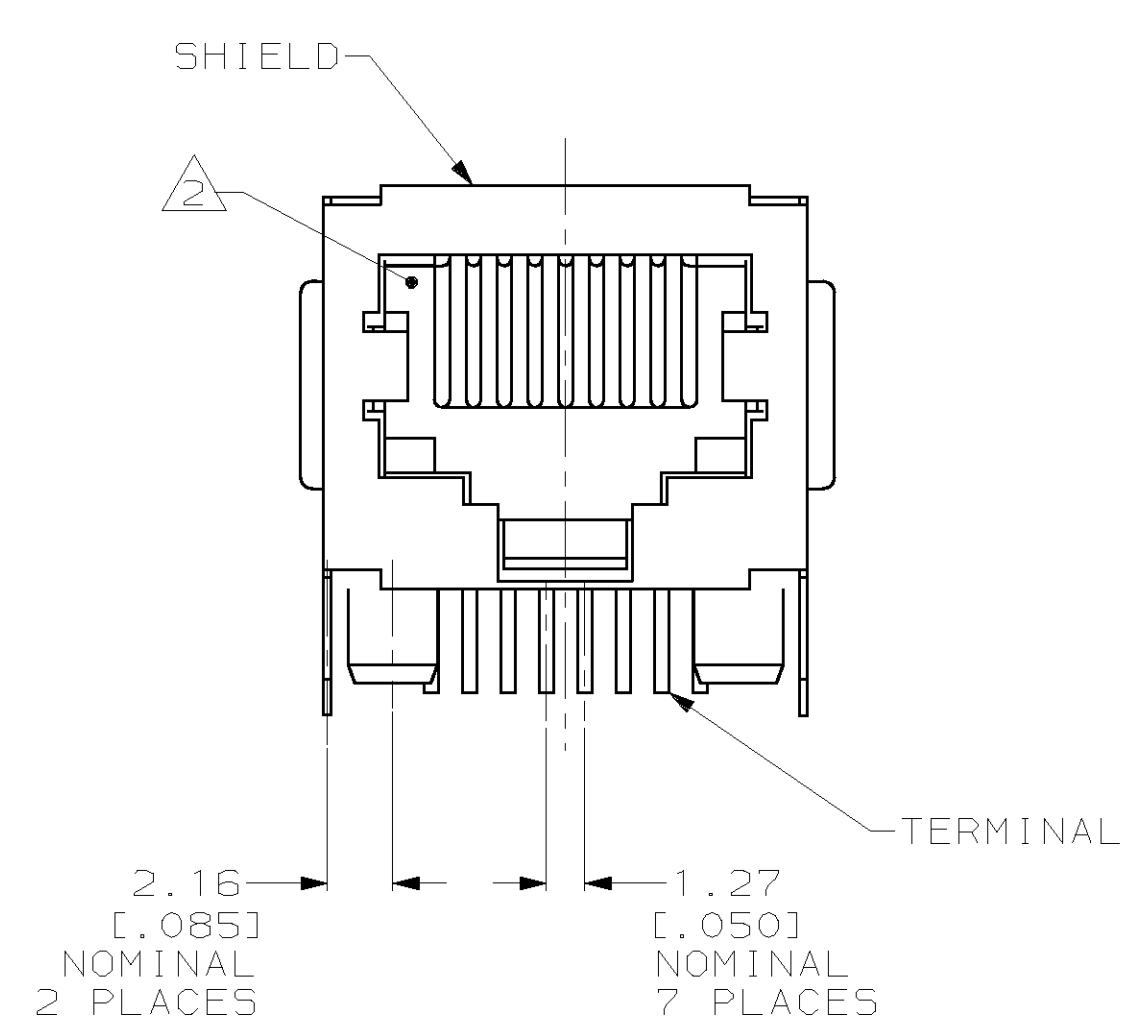
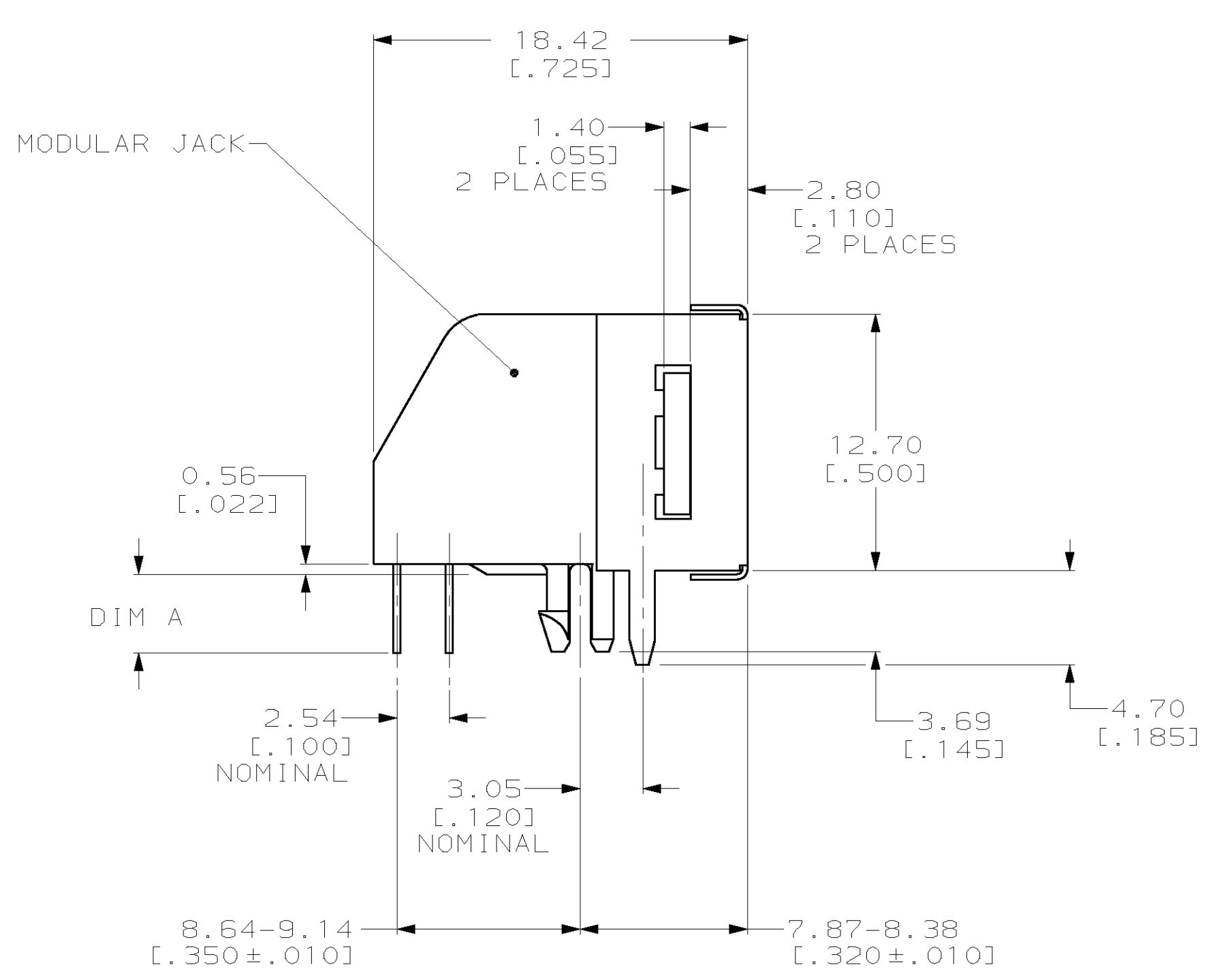
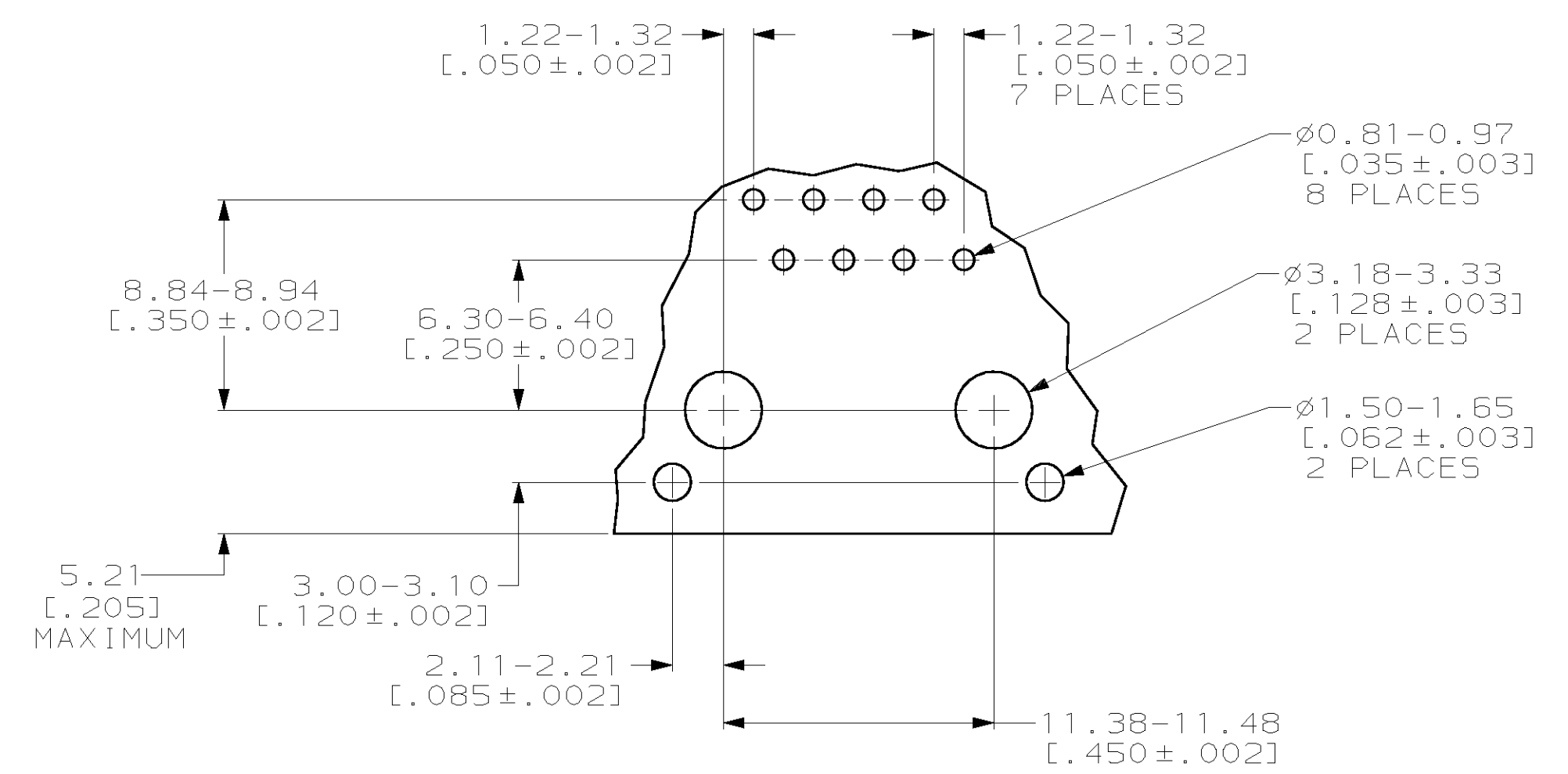


LOC	DIST	REV	DESCRIPTION	DATE	OWN	APVD
AA	22	J	REVISD; EC OUF0-0102-01	17AUG01	DLD	LLV



DETAIL B
SCALE 2:1



SUGGESTED PRINTED CIRCUIT BOARD
MOUNTING HOLE LAYOUT
(VIEW SHOWN IS CIRCUIT SIDE OF BOARD)

- 1 MATERIAL:
HOUSING - PBT POLYESTER BLACK.
TERMINAL - 0.36[.014] THICK PHOS-BRONZE PLATED WITH 1.27µm[.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 2.03µm[.000080] THICK TIN-LEAD IN SOLDER AREA OVER 1.27µm[.000050] THICK NICKEL UNDERPLATE.
SHIELD - 0.25[.010] THICK COPPER ALLOY, TIN-LEAD PLATED.
- 2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F.
- 3 DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.
- 4 BULK PACKAGED IN A TRAY.
- 5 32 ASSEMBLIES PACKAGED PER TUBE, SEE DETAIL B.

1.78-2.79[.09±.02]	△	555153-6
2.54-3.05[.11±.01]	△	555153-5
4.06-4.57[.17±.01]	△	555153-4
3.30-4.32[.15±.02]	△	555153-3
3.30-4.32[.15±.02]	△	555153-1
DIM A	PACKAGED	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED:	0 PLC ±.005	1 PLC ±.005	2 PLC ±.005	3 PLC ±.005	4 PLC ±.005	ANGLES ±.005	FINISH
		△	△	△	△	△	△	△

DRAWN J. GALUCCI/UTA	20MAY94	AMP Incorporated Harrisburg, PA 17105-3608
CHK D. HUSSEY	24MAY94	
APVD J. TONEY	25MAY94	
PRODUCT SPEC		NAME MODULAR JACK ASSEMBLY, 8 POSITION, SHIELDED, LOW PROFILE, RIGHT ANGLE WITH PRINTED CIRCUIT BOARD GROUND AND PANEL STOPS
APPLICATION SPEC		SIZE A1
WEIGHT		CAGE CODE 555153
CUSTOMER DRAWING	SCALE 4:1	SHEET 1 OF 1